



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2026-03-14
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG MD CHAMPION	Representative title	Material Declaration Champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance\* true Legal declaration\* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32L151R6T6 STM32L151R6T6TR	P55W*416XXXV	B	9998	2019-12-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	350	mg	Each	ECOPACK® 2
<b>Identity</b>	<b>Authority</b>			
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
licable; if coating is used or other bulk ter	Tin (Sn), matte	Copper Alloy	

Package designator	Package size	Number of instances	Shape
LQFP	10x10x1.4	68	
Comment			
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
<b>Exemption Id.</b>	<b>Description</b>

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
<b>Exemption Id.</b>	<b>Description</b>

QueryList : California Prop65 list, dated 3rd January 2025	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	true		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	false		
<b>Substance</b>	<b>amount in product (mg)</b>	<b>Application</b>	<b>ppm in product</b>

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
<b>QUERY</b>				
<b>Response</b>				
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				
<b>Hazardous substance</b>				
<b>Lead (Pb)</b>	<b>Cadmium (Cd)</b>	<b>Mercury (Hg)</b>	<b>Hexavalent Chromium (Cr VI)</b>	<b>PBB &amp; PBDE</b>
O	O	O	O	O

QueryList : REACH-4th February 2026	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tantalum, Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	True
All the adhesive impacted complies with GB 33372	true

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

Other Fluorinated Substances	Response
QUERY	Response
The product is containing fluorinated substance.	False
Substance Name, CAS	

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P55W*416XXXV		349.7010		7000000.0	1000001.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.124	mg	supplier	die	Silicon (Si)	7440-21-3		9.802	mg	968194	28030
				supplier	metallization	Aluminium (Al)	7429-90-5		0.028	mg	2766	80
				supplier	metallization	Copper (Cu)	7440-50-8		0.093	mg	9186	266
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.011	mg	1087	31
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	1383	40
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	99	3
				supplier	Passivation	Silicon Nitride	12033-89-5		0.025	mg	2469	71
				supplier	Passivation	Silicon Oxide	7631-86-9		0.150	mg	14816	429
Leadframe (MHT - C194)	Copper and its alloy	89.173	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		86.944	mg	975000	248624
				supplier	ALLOY	Iron (Fe)	7439-89-6		2.096	mg	23500	5992
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.107	mg	1200	306
				supplier	ALLOY	Metallic Phosph	7723-14-0		0.027	mg	300	76
Leadframe (MHT - Ag Plating)	M-011 Other inorganic materials	2.582	mg	supplier	COATING	Silver(Ag)	7440-22-4		2.582	mg	1000000	7383
Glue (Evertch - AP4200)	M-011 Other inorganic materials	0.515	mg	supplier	GLUE	Formaldehyde,	9003-36-5		0.082	mg	160000	236
				supplier	GLUE	1,4-bis(2,3-epo)	2425-79-8		0.008	mg	15000	22
				supplier	GLUE	Formaldehyde,	9003-35-4		0.008	mg	15000	22
				supplier	GLUE	2-butoxyethyl al	112-07-2		0.021	mg	40000	59
				supplier	GLUE	Silver(Ag)	7440-22-4		0.397	mg	770000	1134
Bonding wire (MKE - HTS)	M-011 Other inorganic materials	1.413	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.400	mg	990480	4002
				supplier	BONDING WIRE	Palladium (Pd)	5/3/7440		0.013	mg	9500	38
				supplier	BONDING WIRE	Calcium (Ca)	7440-70-2		0.000	mg	20	0
Encapsulation (Sumitomo - G631H Type C)	M-011 Other inorganic materials	242.847	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		4.857	mg	20000	13889
				supplier	MOLDING COMPOUND	Epoxy Resin B	85954-11-6		9.714	mg	40000	27778
				supplier	MOLDING COMPOUND	Silica Amorpho	60676-86-0		190.635	mg	785000	545138
				supplier	MOLDING COMPOUND	Silica Amorpho	7631-86-9		20.642	mg	85000	59028
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		1.214	mg	5000	3472
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		15.785	mg	65000	45139
Finishing (Sytron - Pure Tin)	M-011 Other inorganic materials	3.047	mg	supplier	COATING	Tin (Sn)	7440-31-5		3.047	mg	1000000	8713